



R&D on Vacuum Components for High Current Accelerators

Y. Suetsugu

on behalf of Vacuum Group, KEK B-factory

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 - Beam duct
 - Inner Coating with Low SEY
 - Bellows and Gate Valve
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Introduction

- Future accelerators, such as Super B-factories, operate with a beam current of **several amperes**, and a bunch lengths of **a few mm**, in order to achieve a high luminosity, $>1 \times 10^{36} \text{ cm}^{-2}\text{s}^{-1}$, for example.
- These beam parameters impose severe challenges to the vacuum system.
 - Beam duct has to manage the synchrotron radiation (SR) power density up to **several tens Wmm⁻²**.
 - Vacuum components should have low beam impedance, and stand up against the intense higher order modes (HOM).
 - Suppression of the **electron cloud instability (ECI)** is a serious problem in a positron ring.
- Development of vacuum components to satisfy the conditions are essential keys to realize the future accelerators.



Introduction

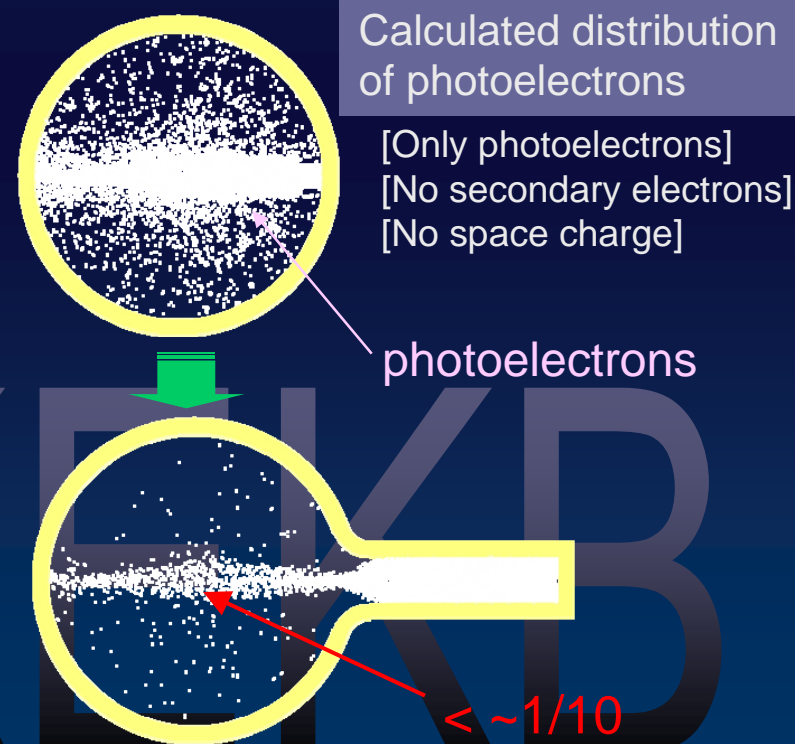
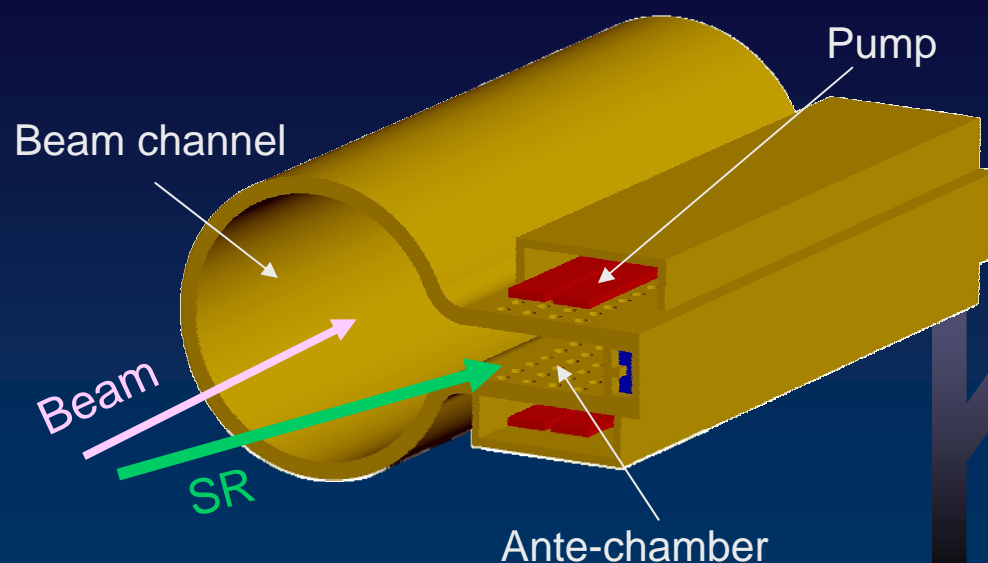
- To meet the demands, R&D on vacuum components has been progressing at KEK, using intense beams of the KEK B-factory ring (KEKB).
 - Low Energy Ring (LER): 3.5 GeV, Max.1.8A (1389 bunches)
 - High Energy Ring (HER): 8.0 GeV, Max.1.4 A (1389 bunches)
- Studied Components:
 - Copper beam ducts with one or two ante-chambers.
 - Inner surfaces with a low secondary electron yield (SEY).
 - Bellows chambers and gate valves with high thermal strength and low beam impedance.
 - Special connection flange with no gap at the connection point.
 - Novel movable mask (collimator) with low beam impedance.
- The results of the R&D are reviewed here.



Beam Duct

- Beam duct with ante-chamber (2003 ~)
 - Ante-chamber = additional chamber
 - Effective to reduce photoelectrons in the beam channel
 - Also effective to dilute the power density of SR
- Use copper

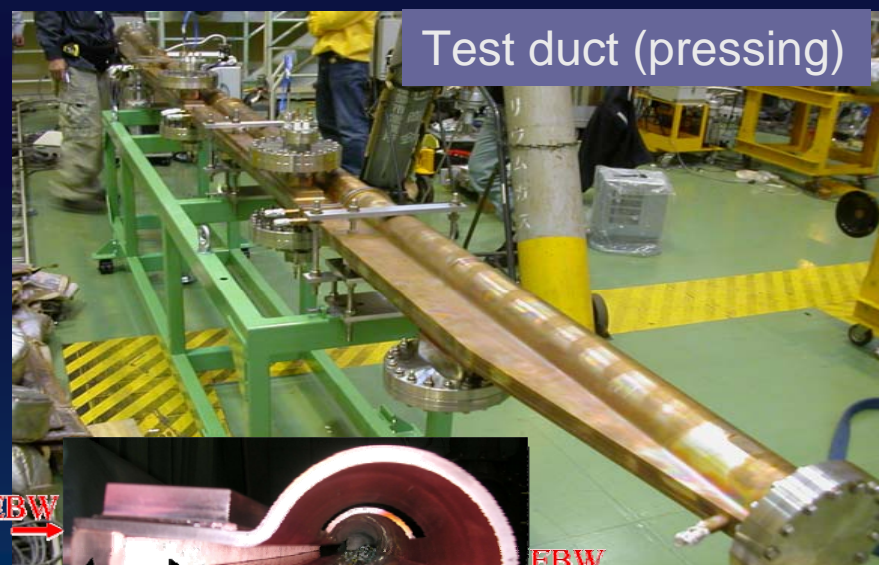
Beam duct with antechamber



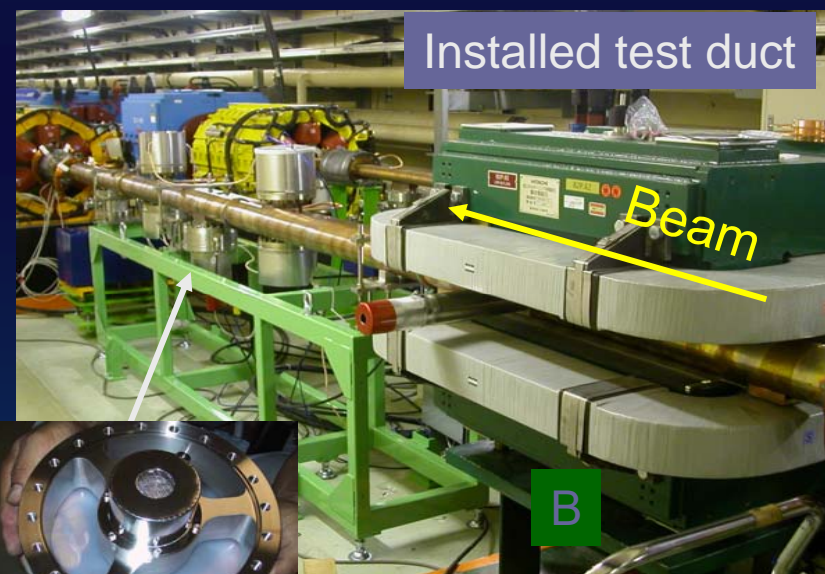


Beam Duct

- Copper ducts with an antechamber for arc sections
 - Manufacturing properties were investigated. → No problem
 - Installed at an arc section of the KEBB positron ring (2003).
 - Reduction of photoelectrons was confirmed.



$\phi = 94 \text{ mm}$
 $h_a = 112 \text{ mm}$
 $t = 6 \text{ mm}$



Electron Monitor
(DC, Collector: +100 V, Repeller: -30V)

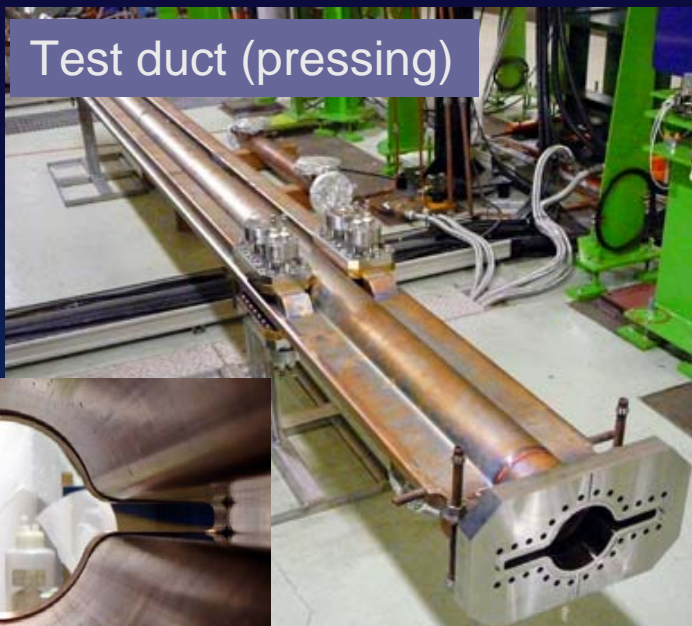


Beam Duct

- Copper duct with two ante-chambers (2005~)
 - Installed into LER wiggler section.
 - **Reduction of photoelectrons was confirmed** again from the measured electron number.
 - **No problem up to 1.7 A.**

$\phi = 94 \text{ mm}$
 $h_a = 224 \text{ mm}$
 $t = 6 \text{ mm}$

Test duct (pressing)



Installed test duct



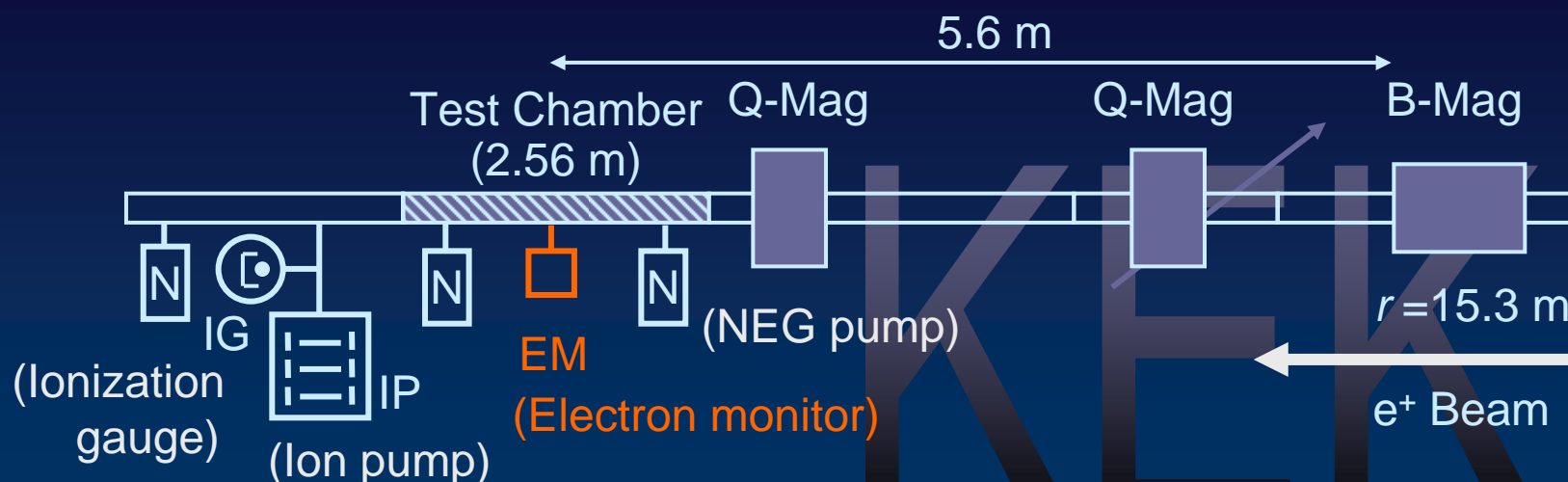
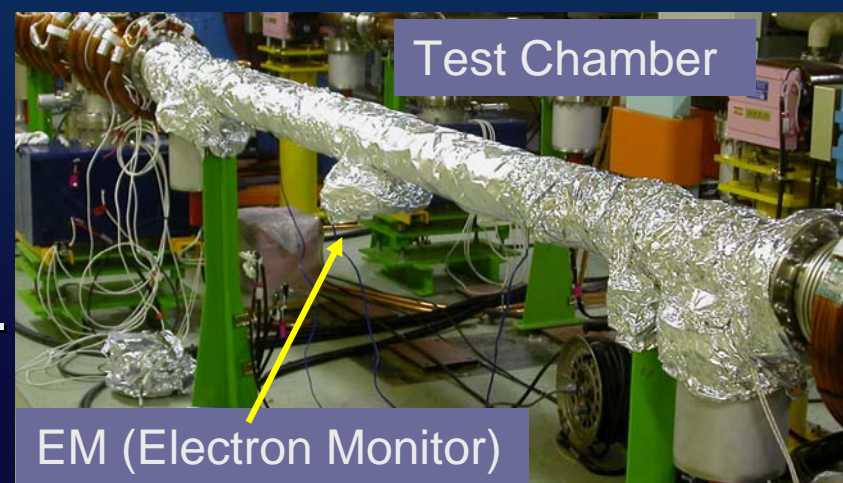


Inner Coating

- Survey of surfaces with a low SEY (2004~)
 - Essential cure against the formation of electron cloud at relatively high current
- Test chambers with **NEG and TiN coatings** were installed in the KEBB positron ring ($\phi 94$).
- **Electron numbers** were measured under the same condition, and compared with each other.
- Photoelectron yield (η_e) and the maximum secondary electron yield (δ_{\max}) were estimated **using a simulation** of the electron current.

Inner Coating

- Experiment at arc section
 - Test chambers were installed at an arc section.
 - Direct SR of 6.4×10^{14} photons/s/m/mA was irradiated at side wall.
 - Realistic condition
 - Incident angle ~ 8 mrad.

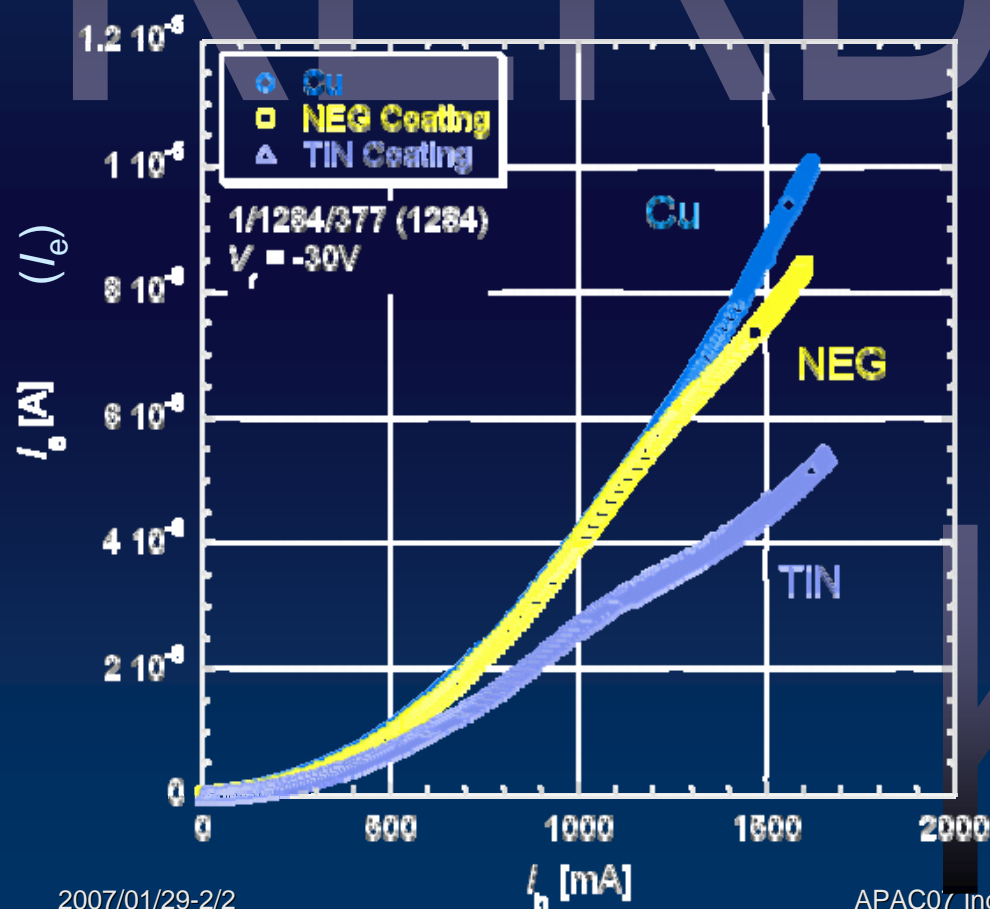




Inner Coating

- Measured electron current (I_e) for Cu, TiN, NEG at the same beam condition

Electron dose >10mC/mm²: After aging

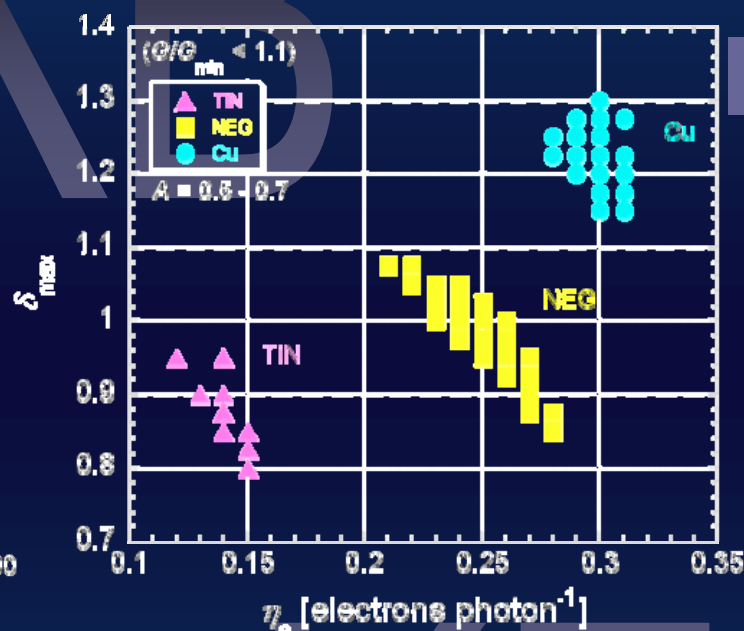
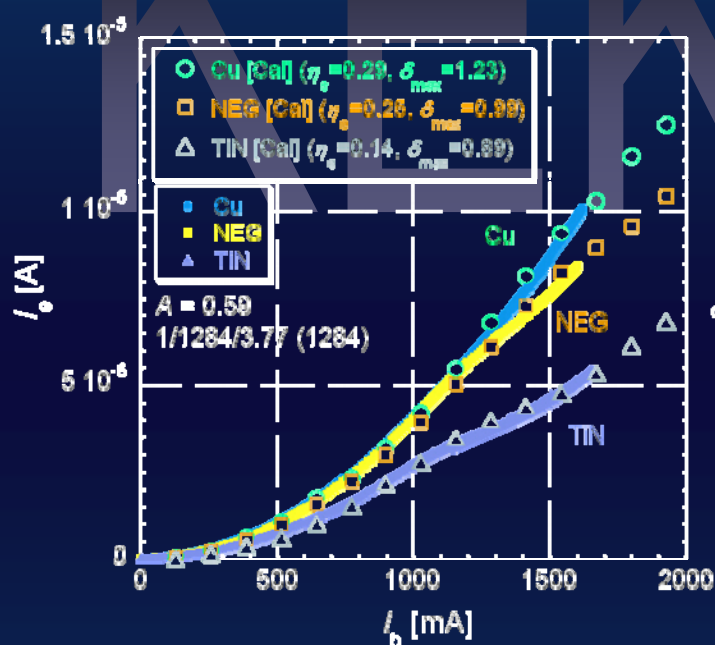


- I_e for NEG coating is almost the same as that of Cu, except for high current.
- I_e for TiN coating is clearly lower than those for Cu and NEG (by a factor of 2).
- TiN seems better from a view point of small electron number in the beam duct.



Inner Coating

- Estimated η_e and δ_{\max} (arc section) by simulation



Fitting

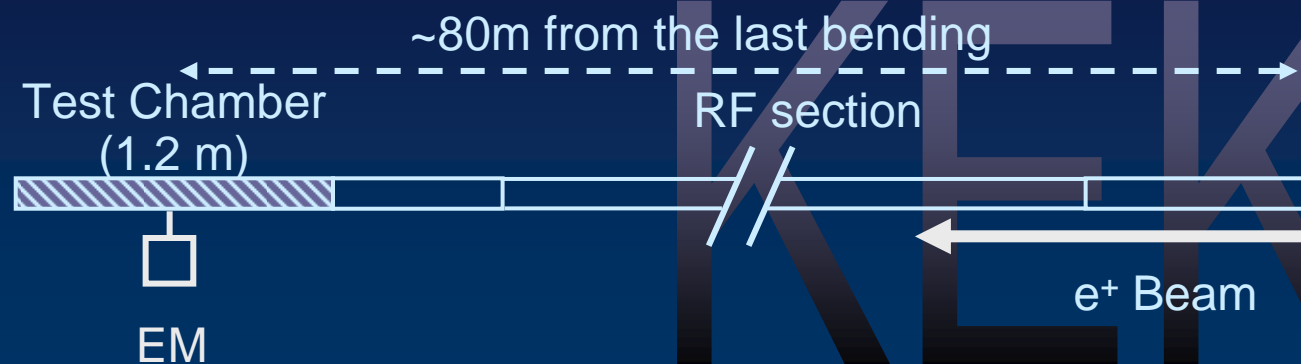
	η_e	δ_{\max}
Cu	0.28-0.31	1.1-1.3
NEG	0.22-0.27	0.9-1.1
TiN	0.13-0.15	0.8-1.0

- TiN seems better from a view point of low δ_{\max} and small η_e .
- δ_{\max} of NEG is lower than Cu, but not so clear due to high η_e .
- δ_{\max} of Cu, NEG and TiN is near to those measured in laboratory after sufficient electron bombardment (after aging).



Inner Coating

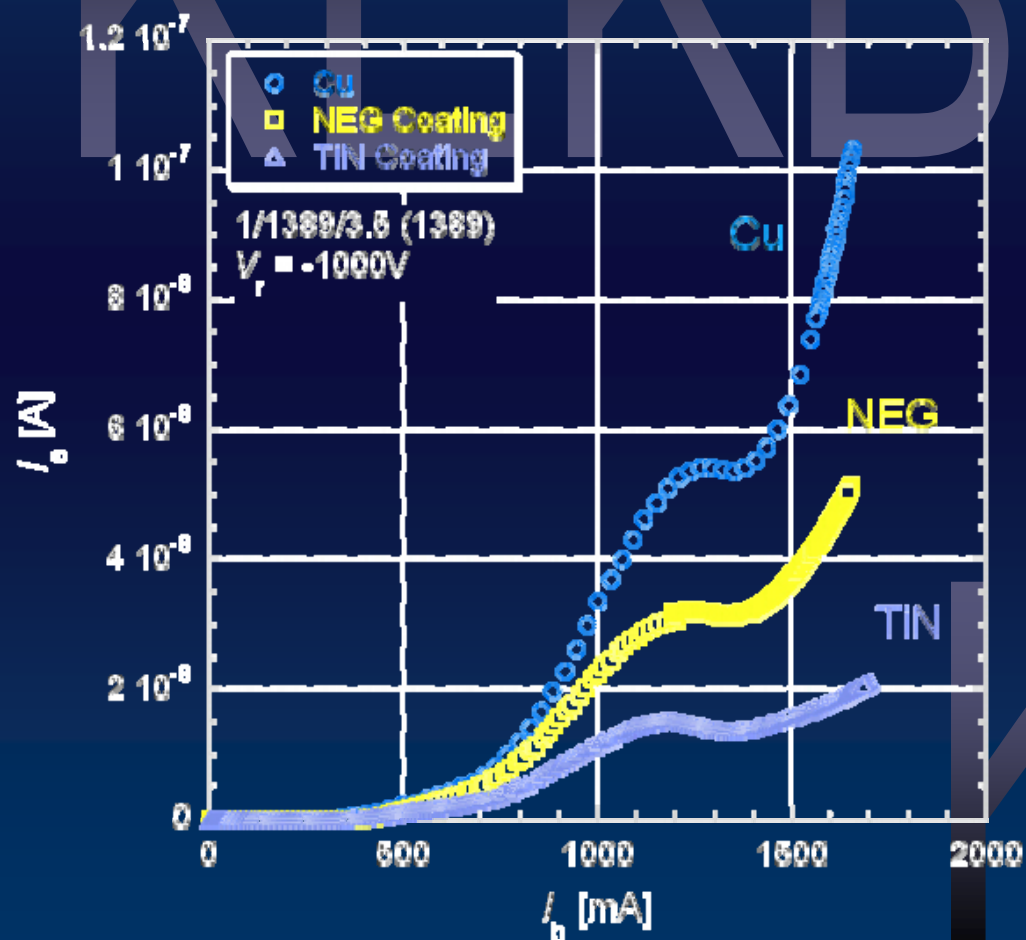
- Measurement at a straight section (2006~)
 - Low direct SR : 3.3×10^{12} photons/s/m/mA (<1/100 of arc)
 - Eliminate the effect of SR
- Copper, TiN coating and NEG coating
 - Incident angle = 0.6 mrad





Inner Coating

■ Measured electron current

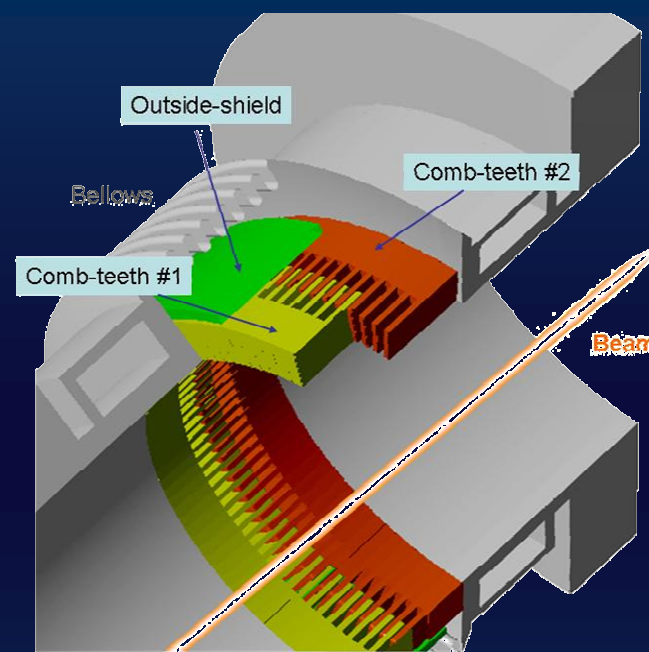


- Electron density for TiN coating is about 1/3 ~ 1/4 of that of copper.
 - Electron density for NEG coating is about 2/3~1/2 of that of copper. The difference between Cu and NEG became clear. ←Small effect of SR.
 - The curves can be reproduced by similar η_e and δ_{\max} .
 - TiN is still better from the view point of low SEY.
- ➡ Combination with ante-chambers



Bellows & Gate Valves

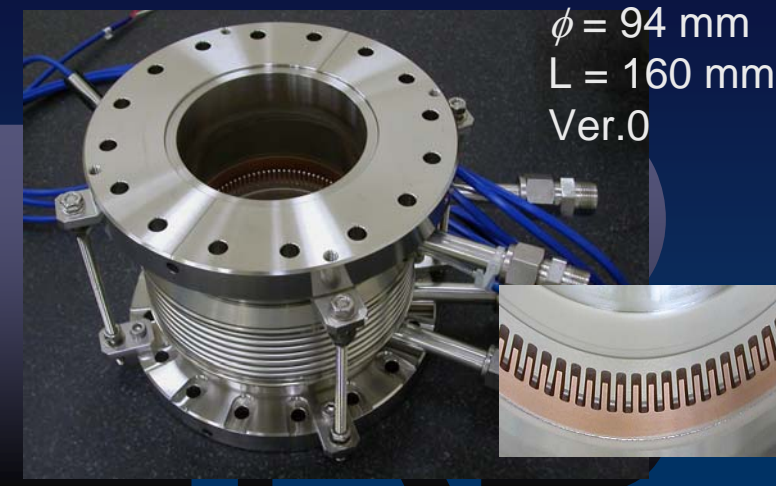
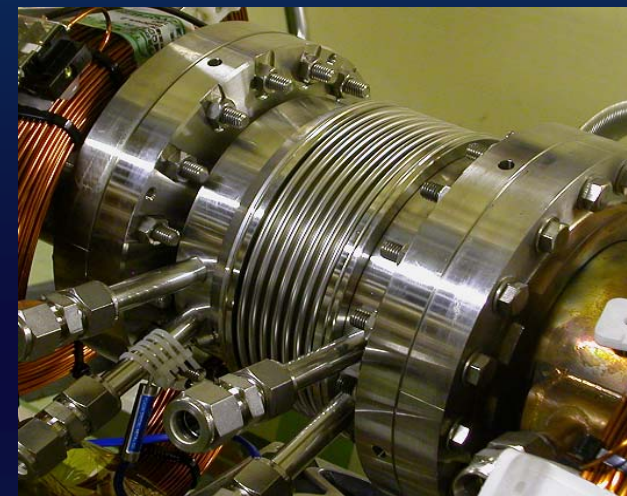
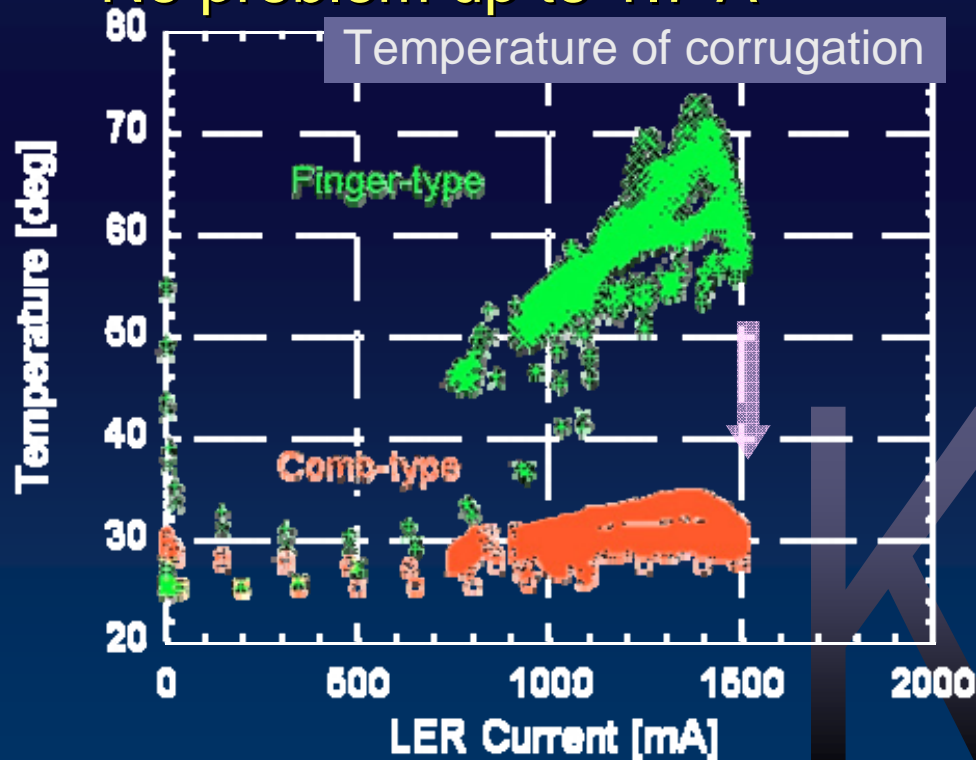
- **Comb-type RF-shield** (2003~)
 - Proposed at KEK
- Nested teeth instead of fingers
 - High thermal strength
 - Small leakage of HOM (TE-mode)
 - $< 1/10$ of finger type
 - Low beam impedance
 - $\sim 1/2$ of finger type
 - Applicable to various aperture
 - Limited offset
 - Complicated structure





Bellows & Gate Valves

- First application to circular bellows (2003~)
 - $\phi 94$, L=160 mm
 - Temperature rise decreases to 1/6
 - No problem up to 1.7 A





Bellows & Gate Valves

- Bellows for a beam duct with ante-chambers (2005~)
 - Easy to apply to a complicated cross section.
 - No problem up to 1.7 A.
 - Inside was checked this winter, and no damage was found.



Comb teeth
(Cu)



Inside view



Whole view

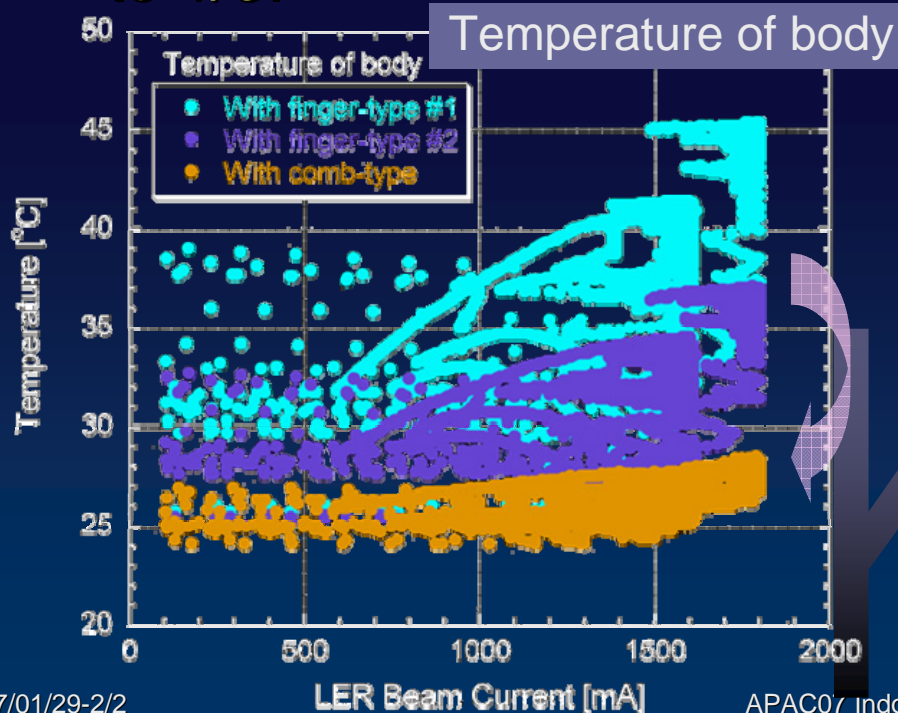
$\phi = 94 \text{ mm}$
 $h_a = 224 \text{ mm}$
 $L = 200 \text{ mm}$
Ver.2



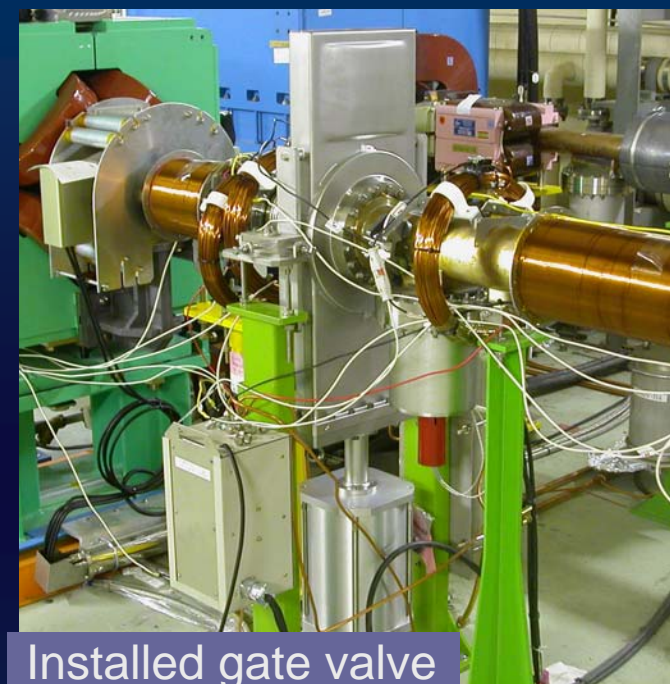


Bellows & Gate Valves

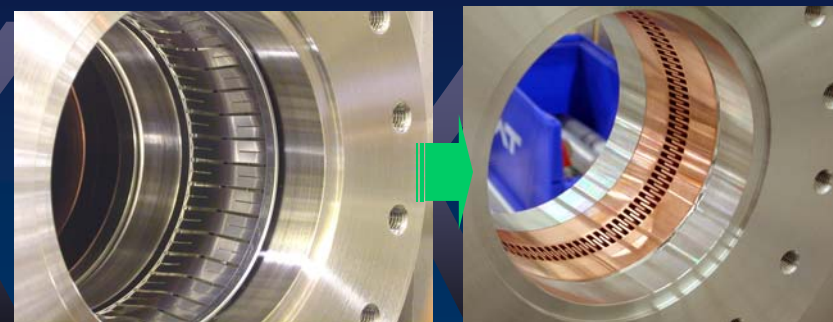
- Circular gate valves (2005~)
 - Simplified structure = No sliding point
 - Collaboration with VAT Vakuumentile AG.
 - Temperature rise of body decreased to 1/3.



$\phi = 94$ mm
L = 95 mm
Ver.2



Installed gate valve

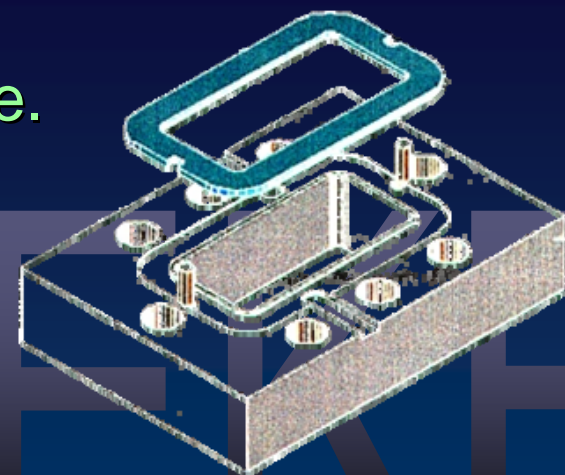
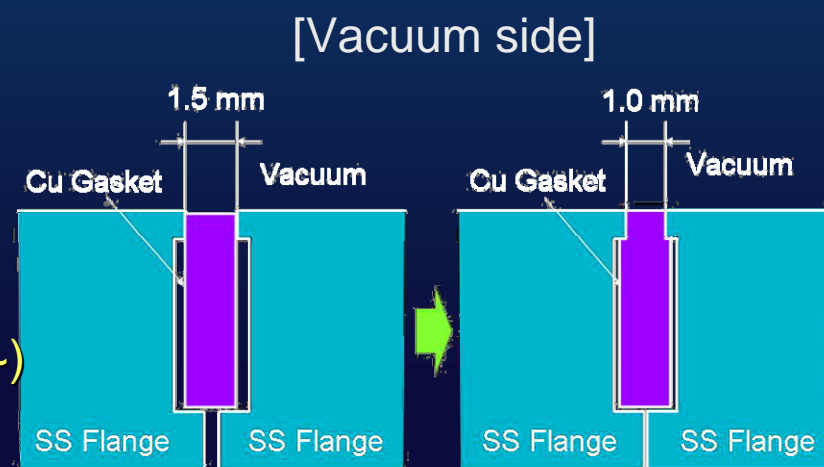


Inside view



Connection Flange

- Important components
 - Large number → Impedance
 - High current → RF-bridge
- **MO** (Matsumoto-Ohtsuka) **Flange** (2004~)
 - Seal a vacuum at only the inner surface.
 - Vacuum seal doubles as RF bridge.
 - No gap and step at the inner surface.
 - Can follow the complicated cross section.
 - Bakable



Rectangular model (for waveguide)



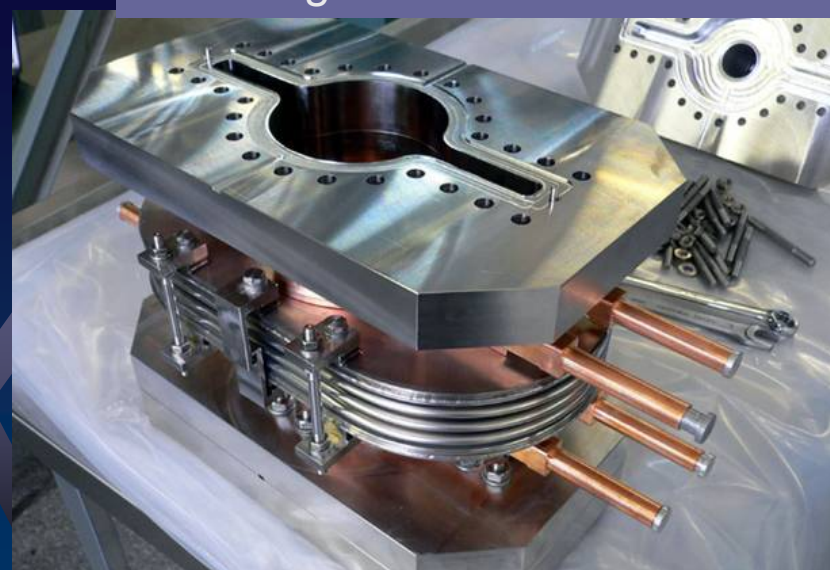
Connection Flange

- Application to bellows chambers and beam ducts (2005~)
 - Vacuum was sealed with a fastening torque of <18 Nm.
 - No problem up to 1.7 A (8 flanges)
 - Applied to new test chambers (28 flanges), and will be tested this year.

MO flange for beam duct



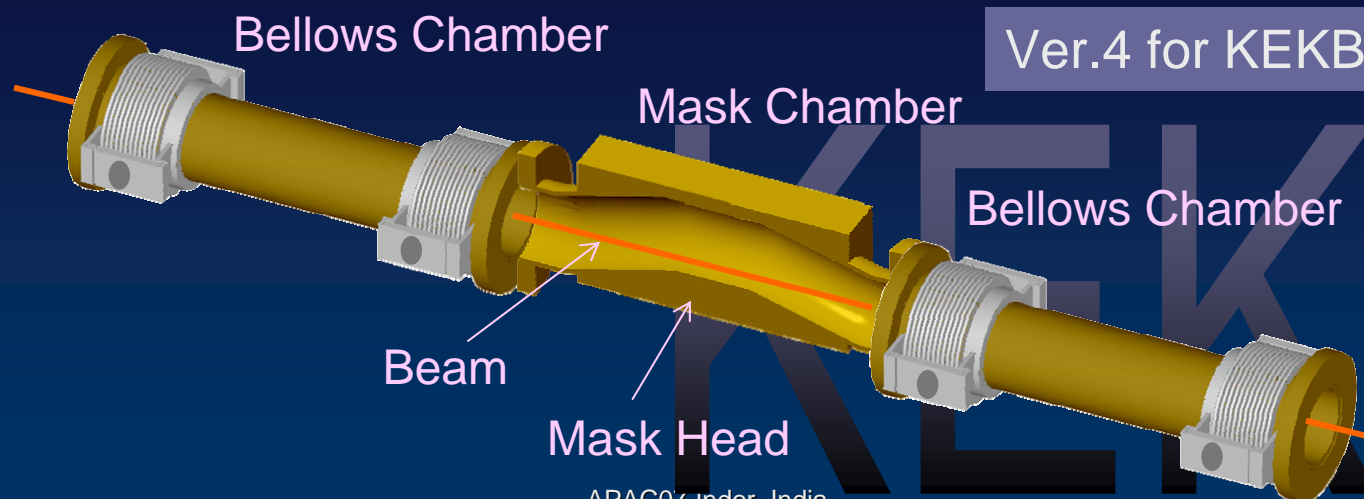
MO flange for bellows chamber





Movable Mask

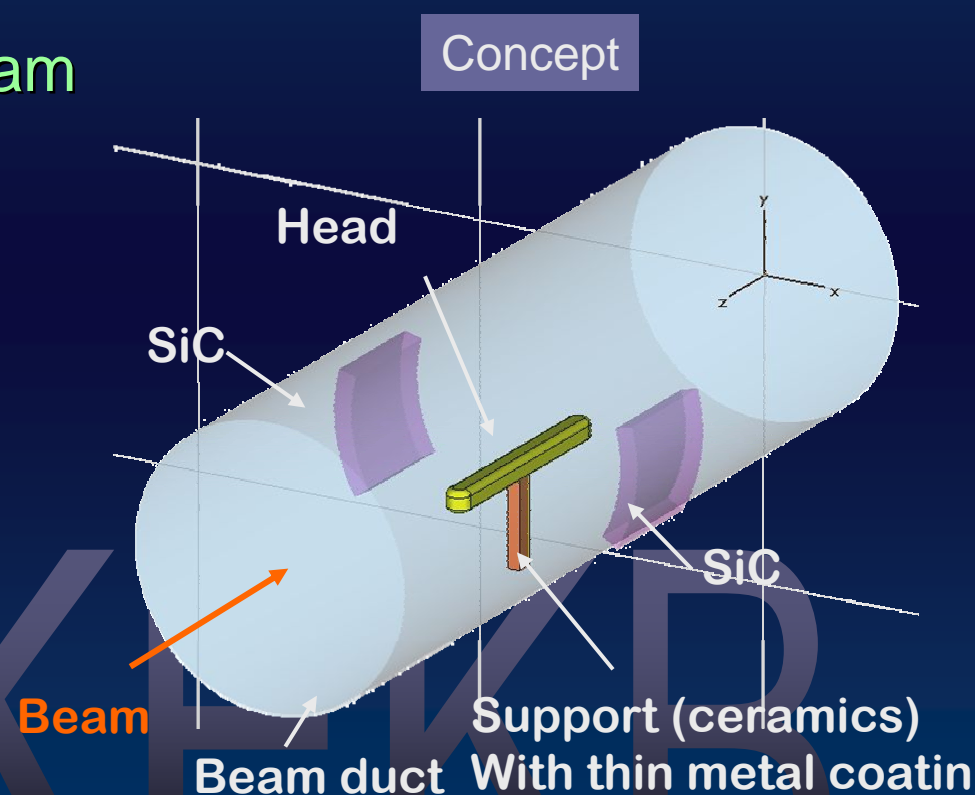
- Movable mask (collimator) (2003~)
 - Indispensable to reduce background of detector
- Problems for high current operation
 - High Impedance ($k = 1 \text{ V pC}^{-1} @ \sigma_z = 3 \text{ mm}$)
 - Damage of head due to direct hitting of bunches
- Basically use the same configuration to present type, but the mask chamber should be changed.





Movable Mask

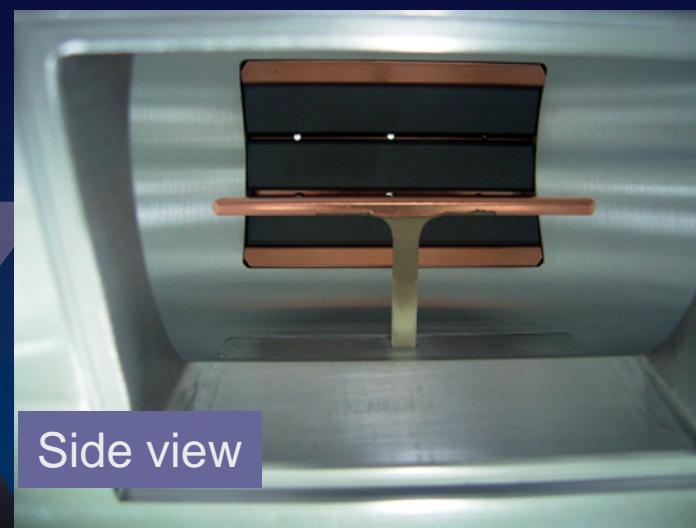
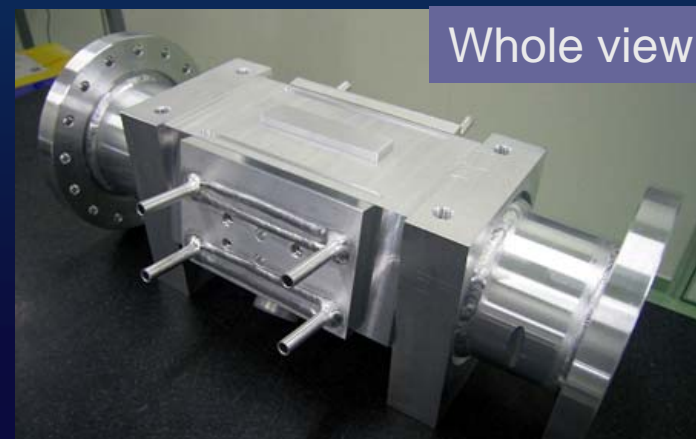
- Proposal of a new mask chamber
 - Ceramic support
 - Little interference with beam
 - k decreased to $\frac{1}{4}$ of Ver.4
 - No problem of CBI
 - With thin metal coating to avoid charge up of head
 - Ceramic head
 - Little damage by beam
 - With HOM absorber (SiC)
 - Absorb trapped modes





Movable Mask

- Trial Model for beam test
 - Vertical mask for LER will be installed this winter.
 - Beam test will start from February.





Summary and Future Plan



- R&D of various vacuum components to adaptable to high current accelerators are proceeding using KEKB.
 - Beam duct with ante-chambers Inner coatings with low SEY, Bellows chambers and gate valves, Connection flanges, and Movable masks
 - R&D is steadily proceeding step by step.
- Next step:
 - Replacement of the present circular beam ducts at a wiggler section (~30m) by that with ante-chambers with TiN coating [this summer].
 - Beam test of a new movable mask.
 - R&D of a clearing electrode for ECI, as an application of the new movable mask (ceramics support).



END

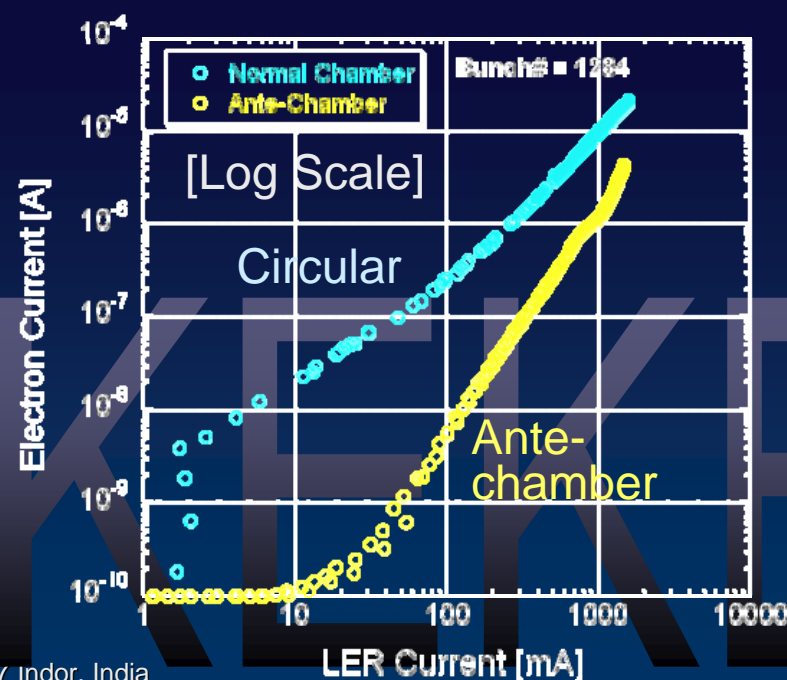
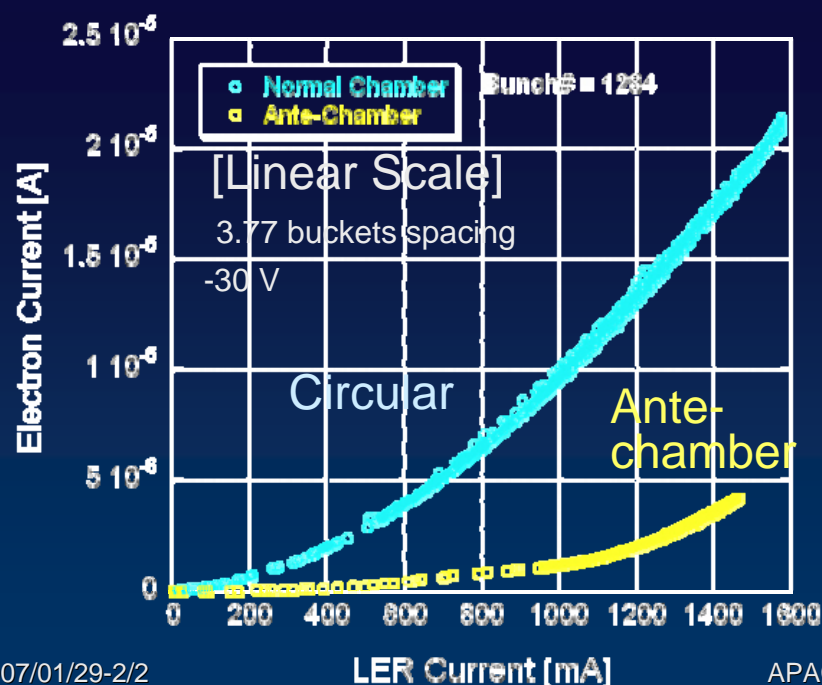


KEKB

KEKB

Beam Duct

- Measurement of electron number
 - Electron current \Leftarrow Number of electrons around beam orbit
 - Compared with a circular simple duct
 - Reduction $< 1/100$ for low beam currents (< 100 mA):
 - Photoelectron is well suppressed.
 - Reduction by a factor of 4 for high currents (> 1500 mA):
 - Secondary electron is important. \rightarrow Surface with low SEY

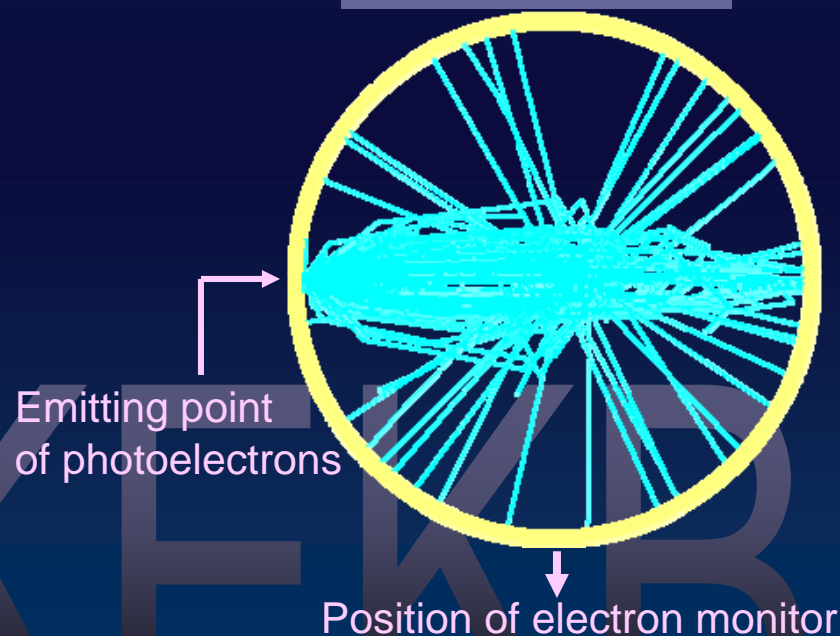




Inner Coating

- Estimation of the max. SEY (δ_{\max}) and the photoelectron yield (η_e) of Cu, NEG and TiN coating, by a simulation.
 - Make use of the behavior of measured electron currents.
- Simulation Method:
 - “Macro” electrons ($\leq 10^4$ electrons) are traced from the emission, and the number of electrons entering the electron monitor) are counted.
 - Curve fitting to the measured electron current.

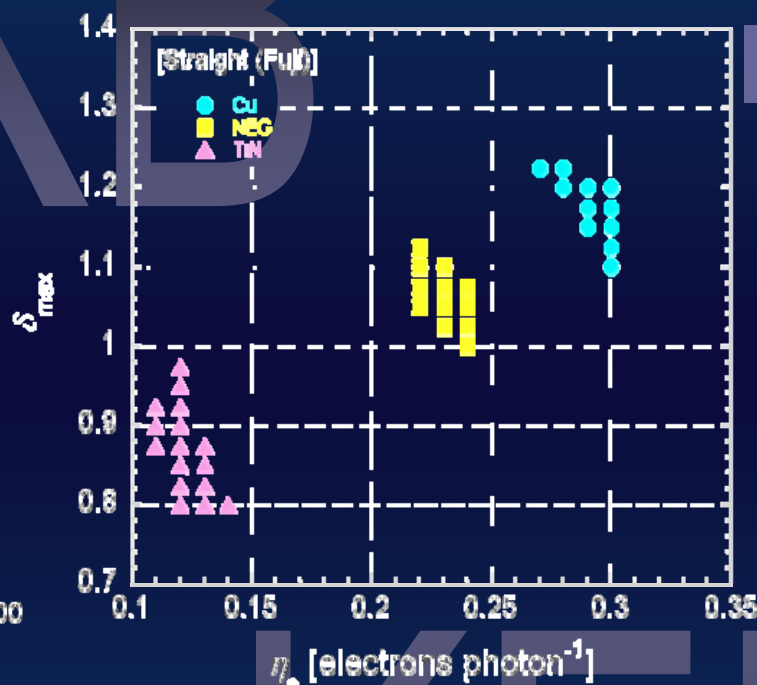
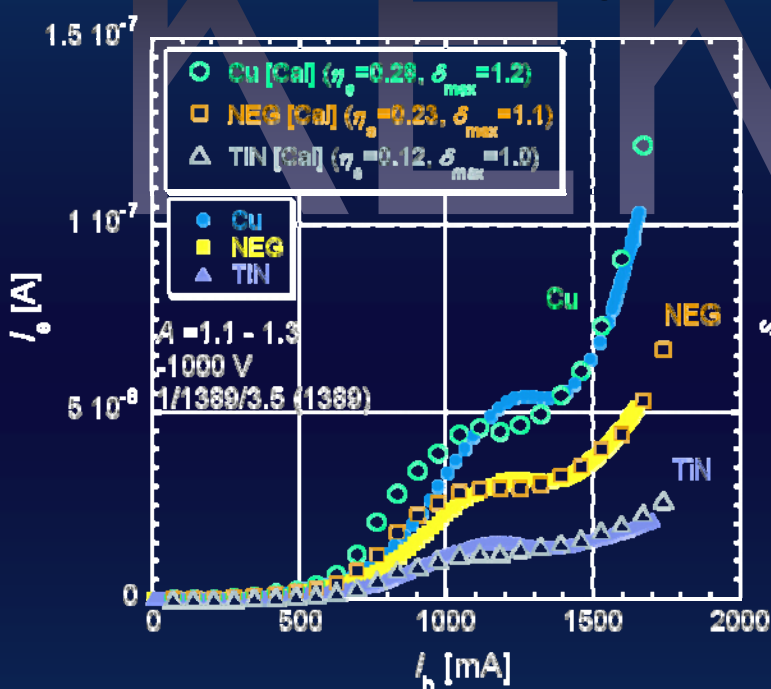
Ex. of simulation





Inner Coating

Estimated η_e and δ_{\max} (straight section)



Fitting at high current

Assuming the same η_e with that of arc section

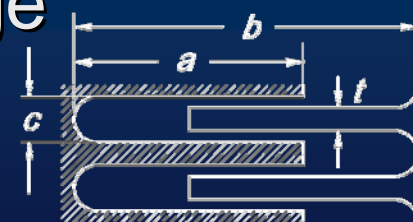
	η_e	δ_{\max}
Cu	0.27-0.30	1.1-1.25
NEG	0.22-0.24	1.0-1.15
TiN	0.11-0.14	0.8-1.0

- Consistent with the measurement at arc section.
- However, SR photons should be higher by a factor of 3 to obtain the measured current.
 - Small incident angle, Scattered photons

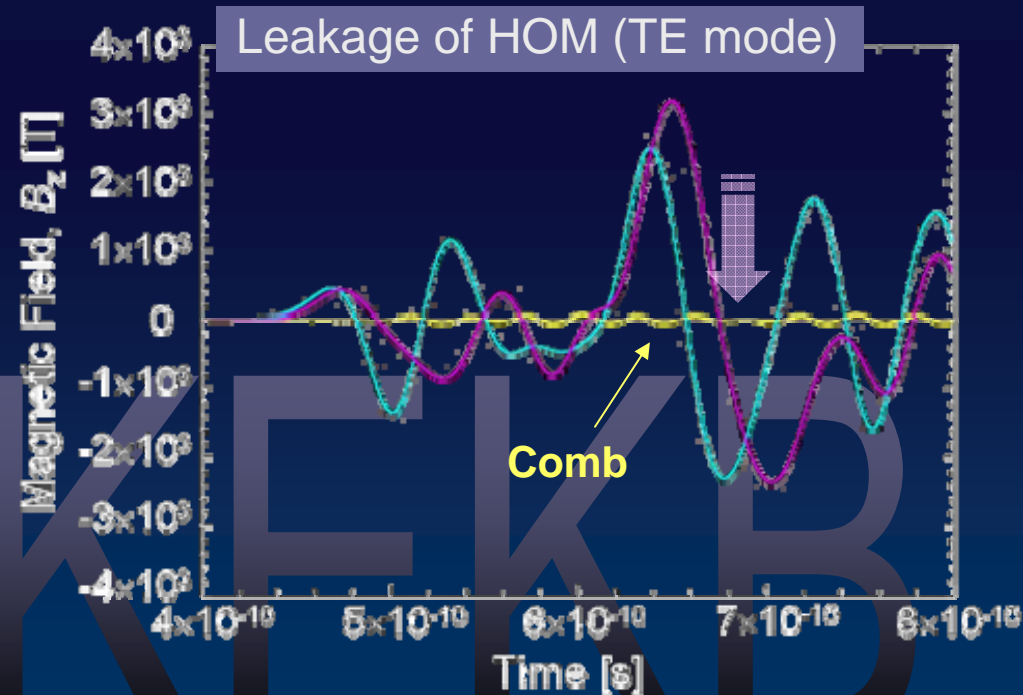
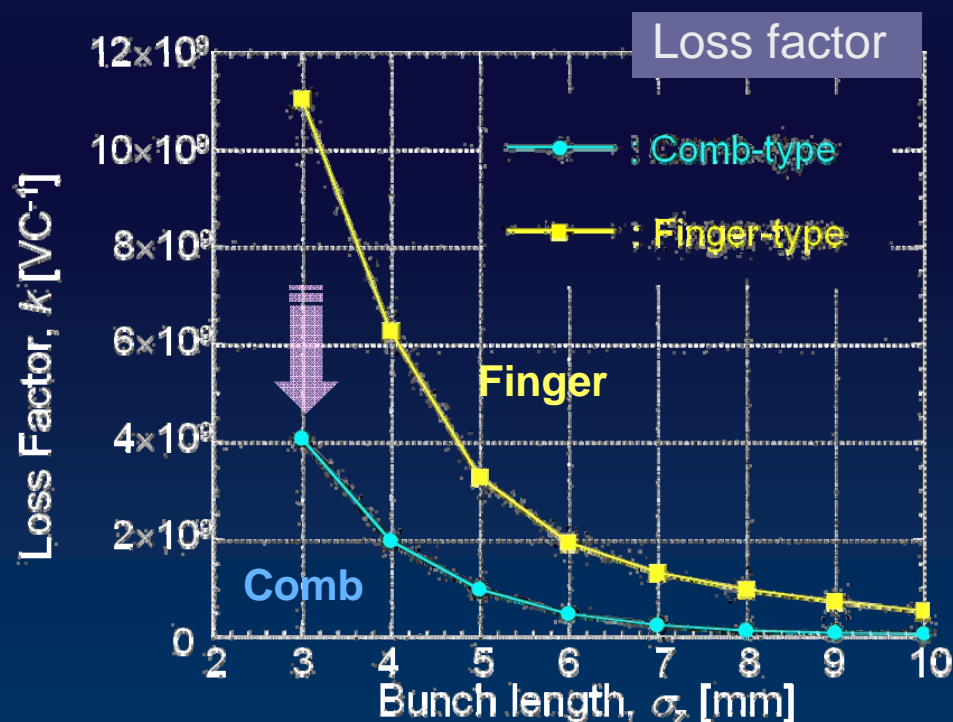


Bellows & Gate Valves

- Calculation of loss factor and HOM leakage
 - Loss factor is about 1/2.
 - HOM leakage is about 1/20.



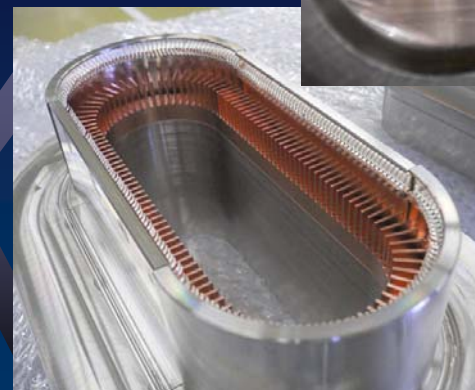
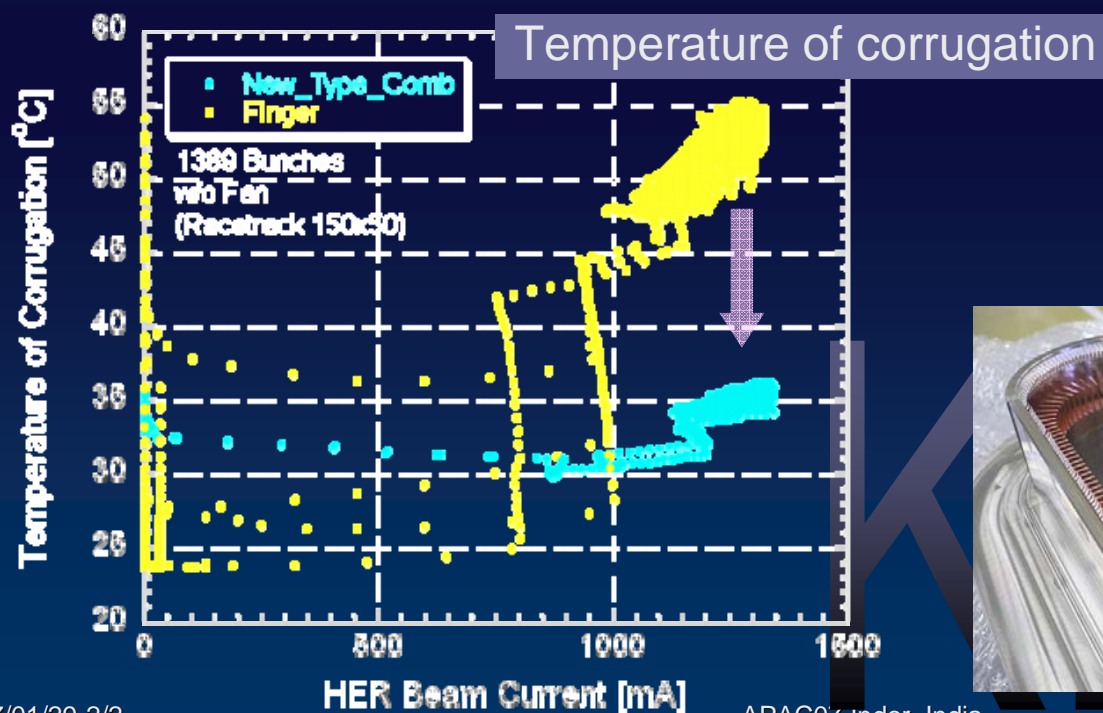
$a=10$ mm, $b=15$ mm
 $c=2$ mm, $d=1$ mm





Bellows & Gate Valves

- Racetrack Bellows (2005~)
 - 150 x 50 mm racetrack
 - No problem up to 1.4 A
 - Temperature rise decreased to 1/3 of that of the conventional bellows.



150x50 mm
L = 200 mm
Ver.2

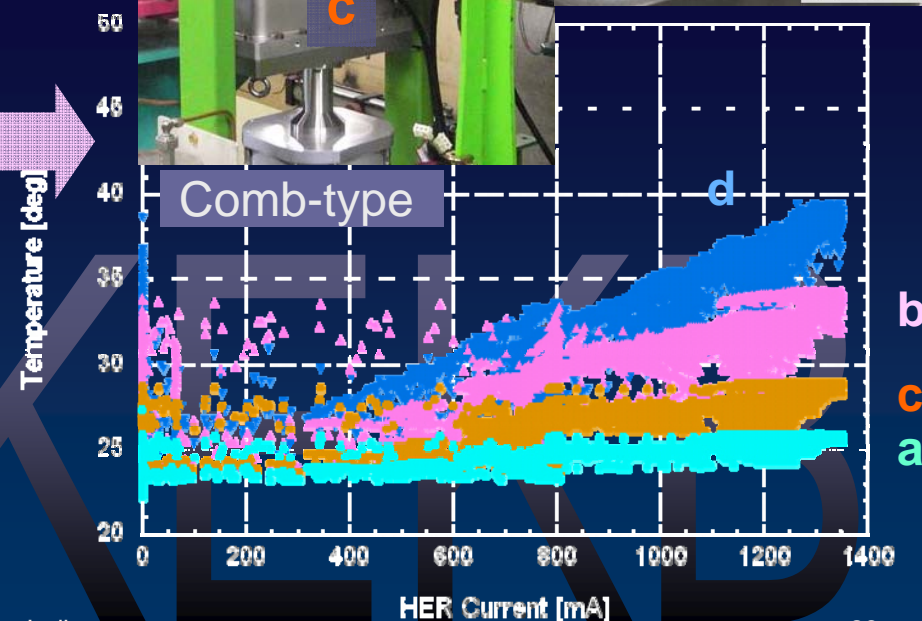
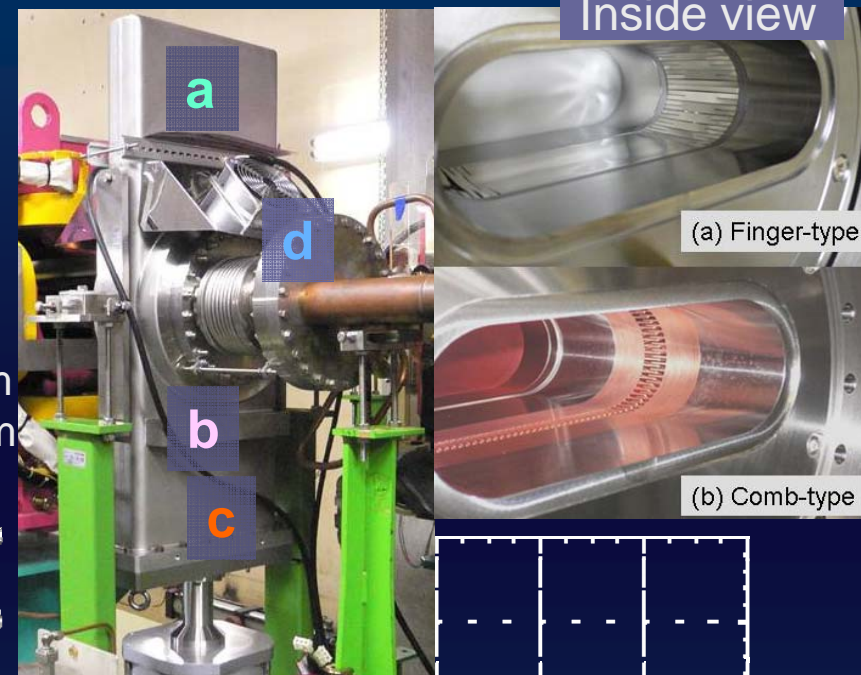
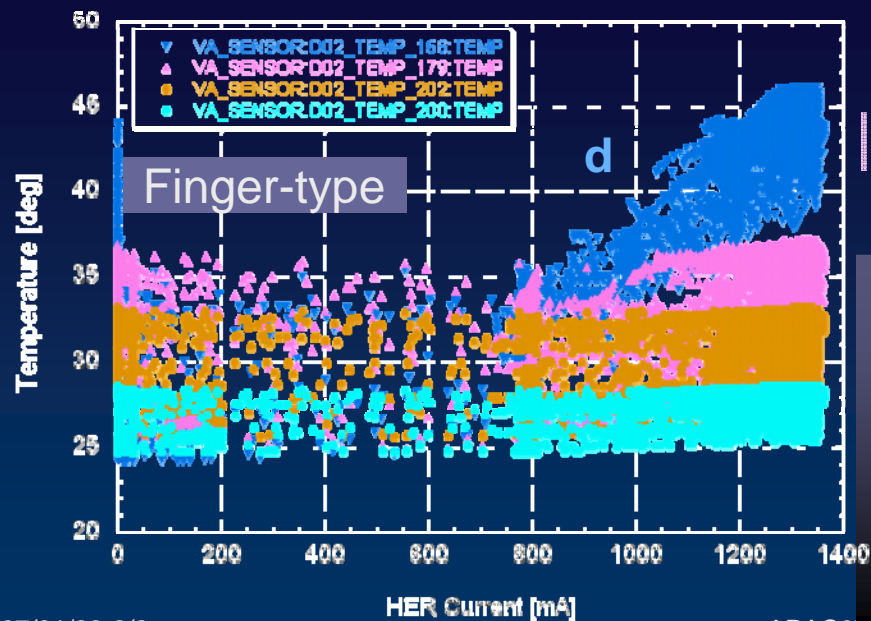


Bellows & Gate Valves

- Racetrack gate valves (2006~)
 - 150x50 racetrack
 - No problem up to 1.4 A
 - Temperature of adjacent bellows also decreased.

160x50 mm
L = 145 mm
Ver.2

d: Bellows

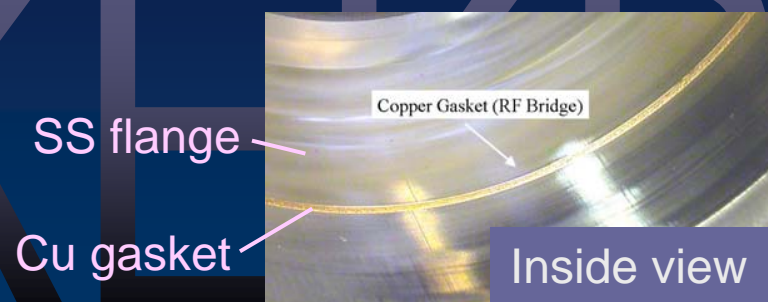
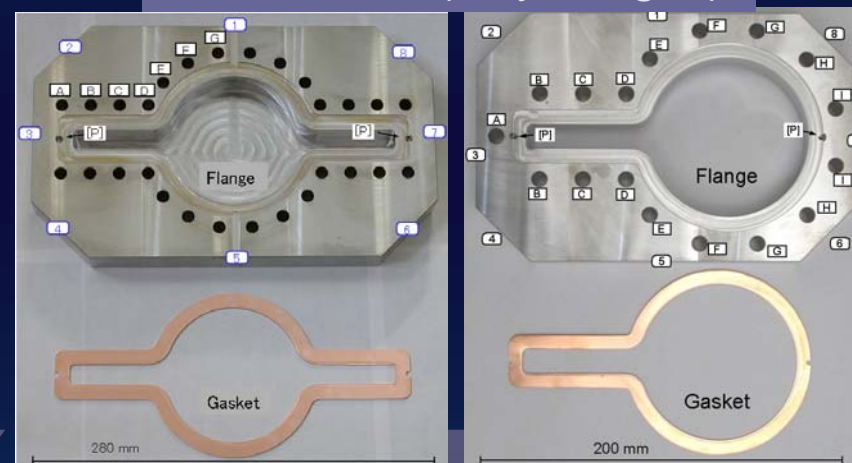
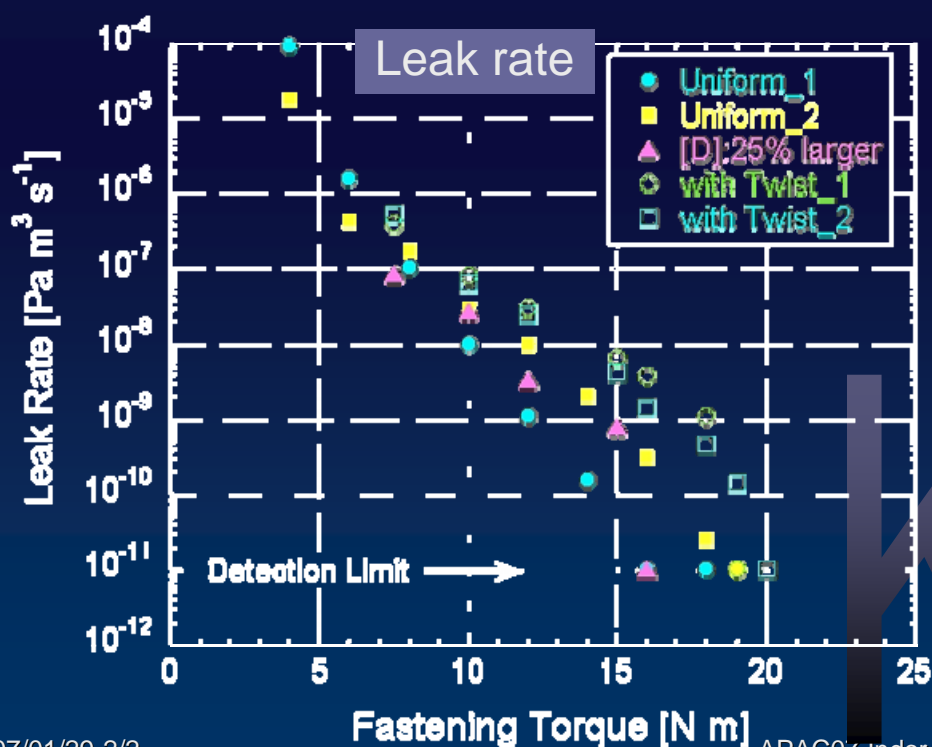




Connection Flange

- Bench test (2004~)
 - Stainless-steel flange and copper gasket (annealed)
 - 180x340 for $\phi 94$ antechamber, 28 M8-bolts along aperture.
 - Vacuum seal at a torque of $\leq 18\text{Nm}$.
 - No problem after baking (200°C)

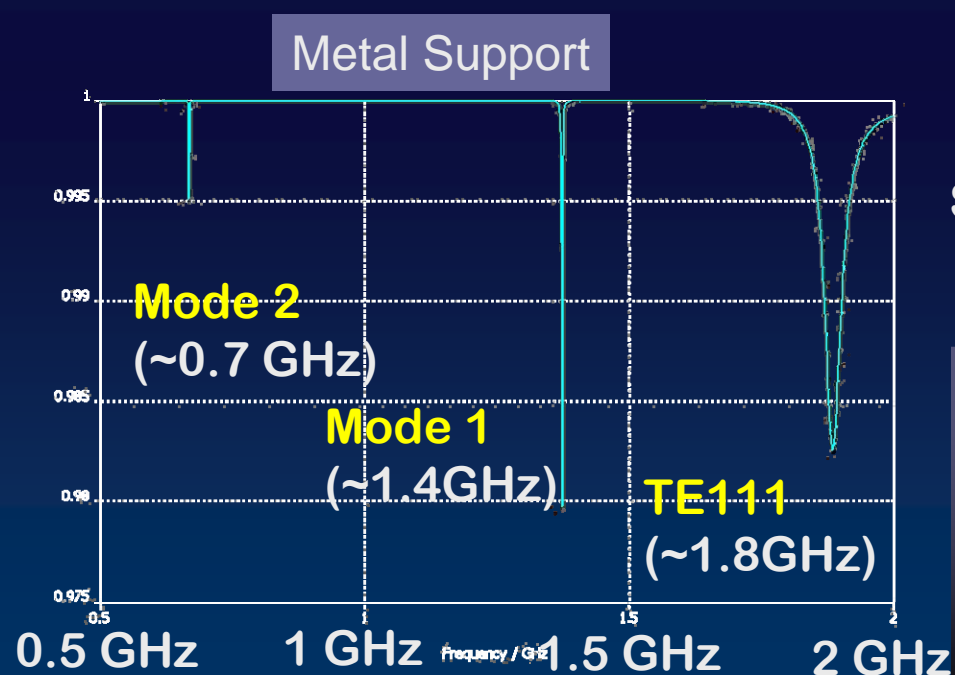
Trial models (only flanges)



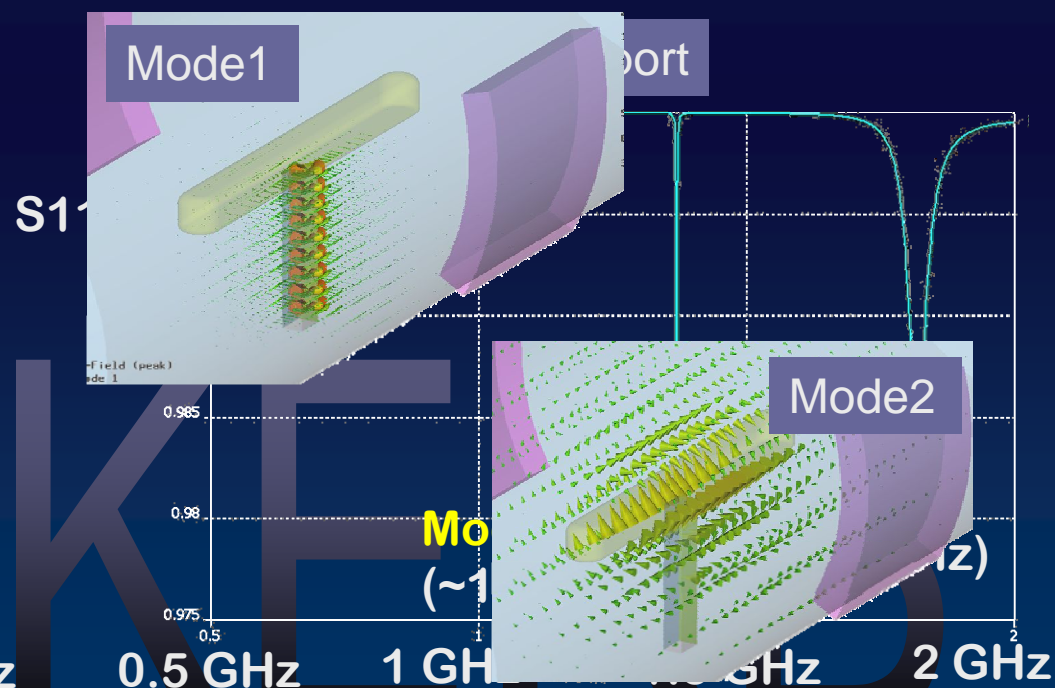


Movable Mask

- Calculation of trapped modes
 - Two trapped modes (Mode1 and Mode2) were found.
 - Mode 1 (=0.7GHz) disappeared for ceramics support.



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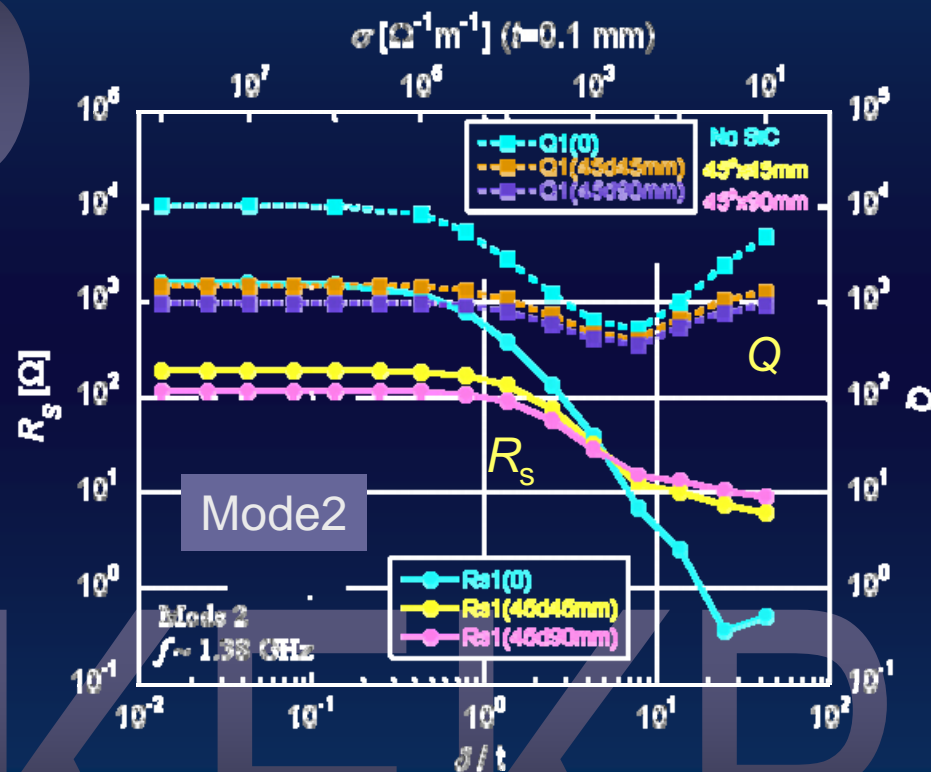
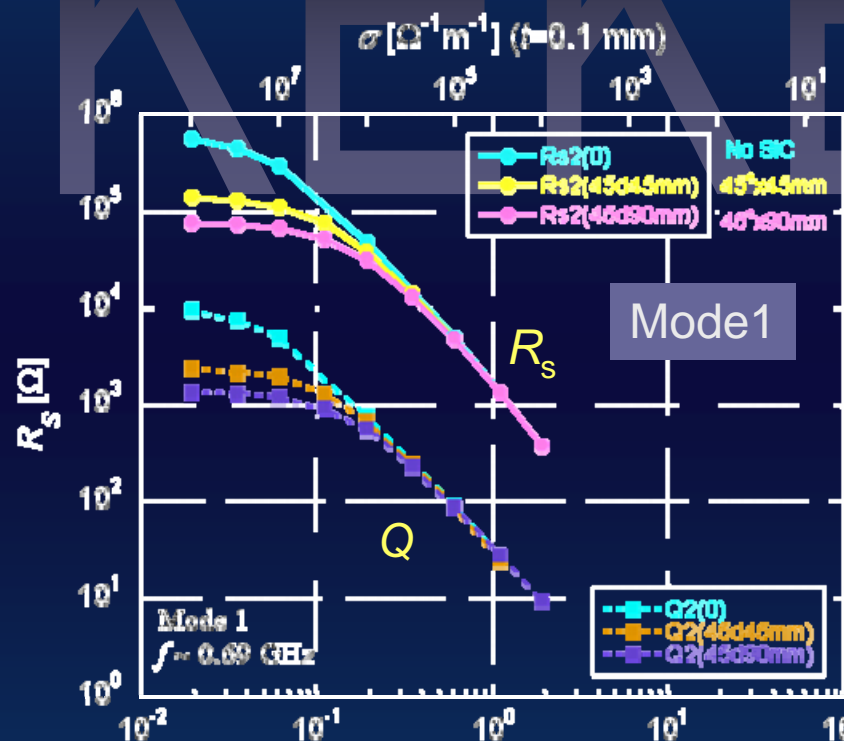
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Movable Mask

- Calculation of longitudinal Impedances (R_s) and Q



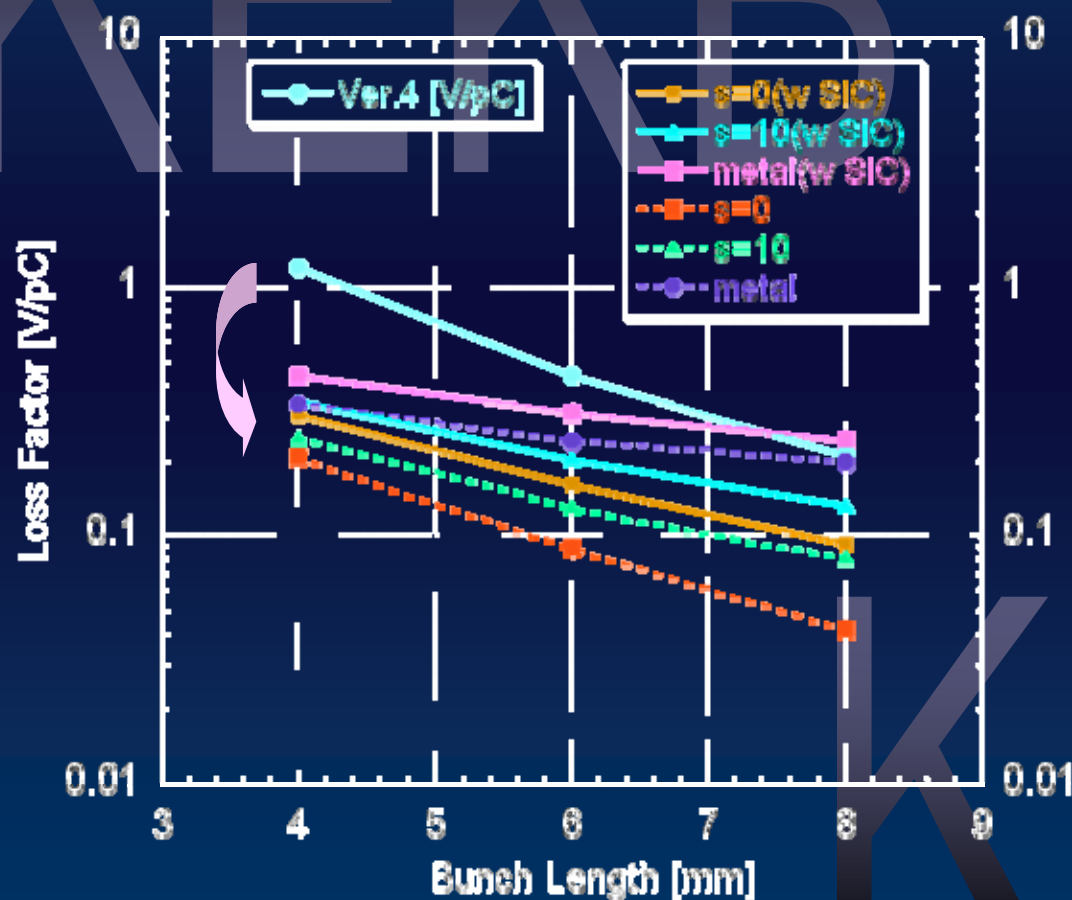
δ/t → High resistivity

- R_s decreases as increasing the resistivity of coating on support.
- No CBI problem for KEKB at full current operation.



Movable Mask

- Calculation of Loss factor



- Loss factor decreases as increasing the resistivity of coating on support.
- Loss factor is about 1/4 of the present Ver.4 mask at $\sigma_z = 4\text{mm}$, when the coating is $1\mu\text{m}$ titanium, for example.



Movable Mask

- Bench test using a test model
 - An atmosphere version was manufactured to check the calculation, and to see the manufacturing property.
 - Measured behavior of trapped modes were well consistent with the calculated one.

Mask head
and support

